Filename: TIDA-00522_BOM.xls

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TIDA-00522

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer	Alternate PartNumber	Alternate Manufacturer
PCB	1		Printed Circuit Board		XX####	Any	-	-
C1, C2, C7,	4	0.01uF	CAP, CERM, 0.01uF, 25V, +/-20%, X7R, 0306	0306	LLL185R71E103MA01L	MuRata		
C8								
C3, C4, C5,	4	2200pF	CAP, CERM, 2200pF, 50V, +/-20%, X7R, 0306	0306	LLL185R71H222MA01L	MuRata		
C6								
C9	1	0.01uF	CAP, CERM, 0.01uF, 16V, +/-10%, X7R, 0603	0603	GRM188R71C103KA01	MuRata		
					D			
C10, C13,	3	10uF	CAP, TA, 10uF, 10V, +/-10%, 0.9 ohm, SMD	3216-18	TPSA106K010R0900	AVX		
C14								
C11		0.1uF	CAP, CERM, 0.1uF, 10V, +/-10%, X5R, 0402	0402	C1005X5R1A104K	TDK	-	-
C12, C17		0.01uF	CAP, CERM, 0.01uF, 25V, +/-10%, X7R, 0402	0402	C1005X7R1E103K	TDK		
C18	1	3.3pF	CAP, CERM, 3.3 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402	GRM1555C1E3R3CA01	MuRata		
					D			
GND,	3	Black	Test Point, TH, Multipurpose, Black		5011	Keystone Electronics		
TPG1,								
TPG2								
IN+, IN-,	6		Connector, SMT, End launch SMA 50 ohm	SMA End Launch	142-0701-851	Emerson Network Power	-	-
OUT+, OUT-								
, PD, Vcm								
Jpd	1		Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator	TSW-102-07-G-S	TSW-102-07-G-S	Samtec, Inc.	-	-
R1, R2, R3,	5	100	RES, 100, 1%, 0.063 W, 0402	0402	CRCW0402100RFKED	Vishay-Dale		-
Ri+, Ri-								
Rcm+, Rcm-	2	1.00k	RES. 1.00k ohm. 1%. 0.1W. 0603	0603	CRCW06031K00FKEA	Vishav-Dale		
			-, ,, - ,					
Ro+, Ro-	2	40.2	RES, 40.2 ohm, 1%, 0.063W, 0402	0402	CRCW040240R2FKED	Vishay-Dale		
Rsd	1	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale		
SH-Jpd_1-	1	1x2	Shunt, 100mil, Gold plated, Black		382811-6	AMP		
OPEN								
U1	1		8GHz Ultra Wideband Fully Differential Amplifier,	RMS0014A	LMH5401IRMS	Texas Instruments		None
			RMS0014A					
V+	1	Red	Test Point, TH, Multipurpose, Red		5010	Keystone Electronics		
V-	1	Yellow	Test Point, Multipurpose, Yellow, TH	Yellow Multipurpose	5014	Keystone		
				Testpoint				
C15, C16	0		CAP, CERM, xxxF, xxV, [TempCo], xx%,	0603	Used in BOM report	Used in BOM report	-	-
			[PackageReference]					
RB+, RB-,	0		RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report	-	-
Rtcm								
Rf+, Rf-	0	174	RES, 174, 1%, 0.063 W, 0402	0402	CRCW0402174RFKED	Vishay-Dale		

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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